

ABSTRACT OF THE DISCLOSURE

In order to prevent, when a chip component is brazed to pads of a conductive wiring layer, short-circuiting by a fused brazing material from short-circuiting between the pads, a hybrid semiconductor circuit comprises a chip component 43 with terminal electrodes 46 formed at both ends thereof, a first conductive wiring layer 37 on which a plurality of the pads 38 are provided to correspond to the terminal electrodes 46, and an overcoat resin 39 for covering the first conductive wiring layer 37 excluding the pads 38, and the terminal electrodes 46 of the chip component 43 is adhered to the pads 38 by a conductive adhesive 57, and an insulating adhesive 58 is provided between the pads 38.